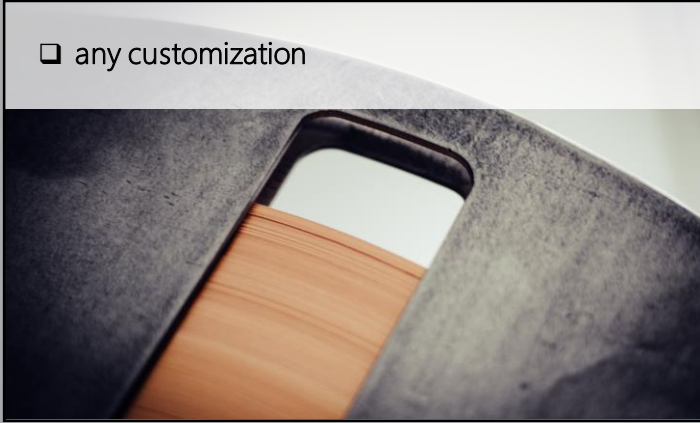
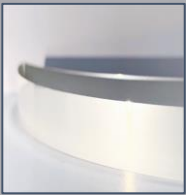


- wire for LN₂



| Parameter | Value | | |
|-------------------------------------|----------------|-----------|-----------|
| Substrate thickness | 40, 60, 100 μm | | |
| Tensile strength * | > 500 MPa | | |
| Critical deformation* | 0.45% | | |
| Critical bend diameter * | < 22 mm | | |
| Wire width, mm | 4.0 | 6.0 | 12.0 |
| Min. critical current @ 77 K, s.f. | 100-200 A | 150-300 A | 300-700 A |
| Critical current standard deviation | ≤ 3% | | |

* I_c retention ≥ 95%



silver



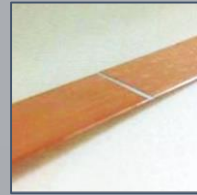
copper



solder



insulation



low resistance joints

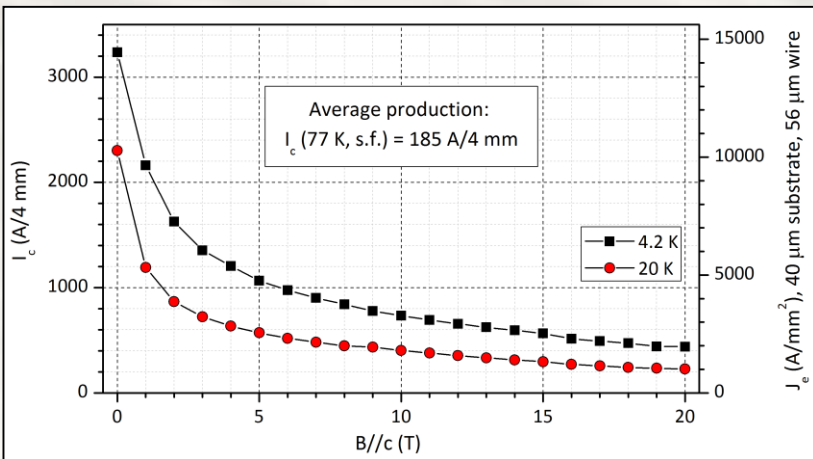


lamination and stacks

- wire for in-field applications

Critical current for 4 mm wire at high magnetic fields and low temperatures

| | s.f. | 5 T | 10 T | 15 T | 20 T |
|-------|---------------|---------------|--------------|--------------|--------------|
| 20 K | 2300 A | 570 A | 400 A | 300 A | 220 A |
| 4.2 K | 3200 A | 1060 A | 730 A | 560 A | 440 A |



1000 A/mm² @ 20 K, 20 T
 2000 A/mm² @ 4.2 K, 20 T

world record!
 commercially available